

**深 圳 市 雅 晶 鑫 有 限 公 司**  
***Shenzhen Yajingxin Electron Co.,Ltd***

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***SPECIFICATION FOR APPROVAL***

**CUSTOMER**

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**NOMINAL FREQUENCY**

8 ~ 50MHZ

**HOLDER TYPE**

SMD-5032-2PIN

**SPEC. NO. ( P/N )**

\_\_\_\_\_

**CUSTOMER P/N**

\_\_\_\_\_

**ISSUE DATE**

Aug.3,2016

APPROVED	PREPARED	QA
<b>APPROVED BY CUSTOMER :</b>		<b>AVL Status</b>
<b>Please return one copy with approval toHLC</b>		

# TYPE HF SEAM SEALED X'TAL

## ELECTRICAL SPECIFICATIONS

HLC Parts Number :

Item	Symbol	Specifications				Notes
		Min	Type	Max	Units	
Nominal frequency	FO	8 ~ 50			MHz	
Mode of Oscillation	OT	Fundamental				
Load Capacitance	LC	20		pF		
Frequency Tolerance	FT	$\pm 20$		ppm	at 25 $\pm 3$	
Frequency Stability		$\pm 30$		ppm	with working temperature Reference to 25	
Working temperature range	TR	-40~85				
Drive Level	DL	100		$\mu$ W		
Series Resonant Resistance RR	CI/RR			$\Omega$	Max.	
Shunt Capacitance C0	C0	7		pF		
Aging		$\pm 3$		ppm/yr.		
Storage temperature range		-55 ~ 125				
Unit Weight				g		

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**MARKING**

中性

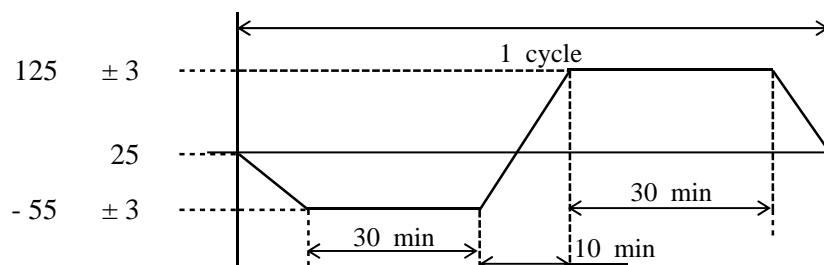
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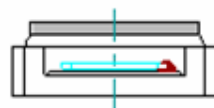
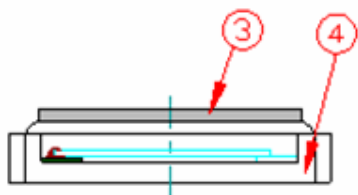
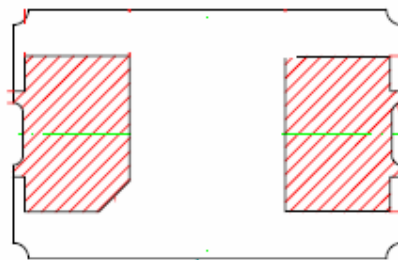
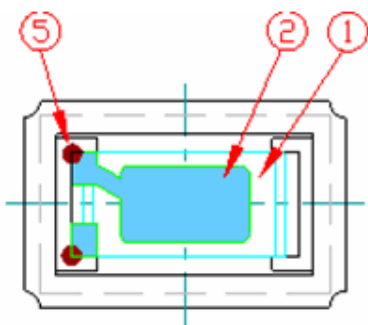
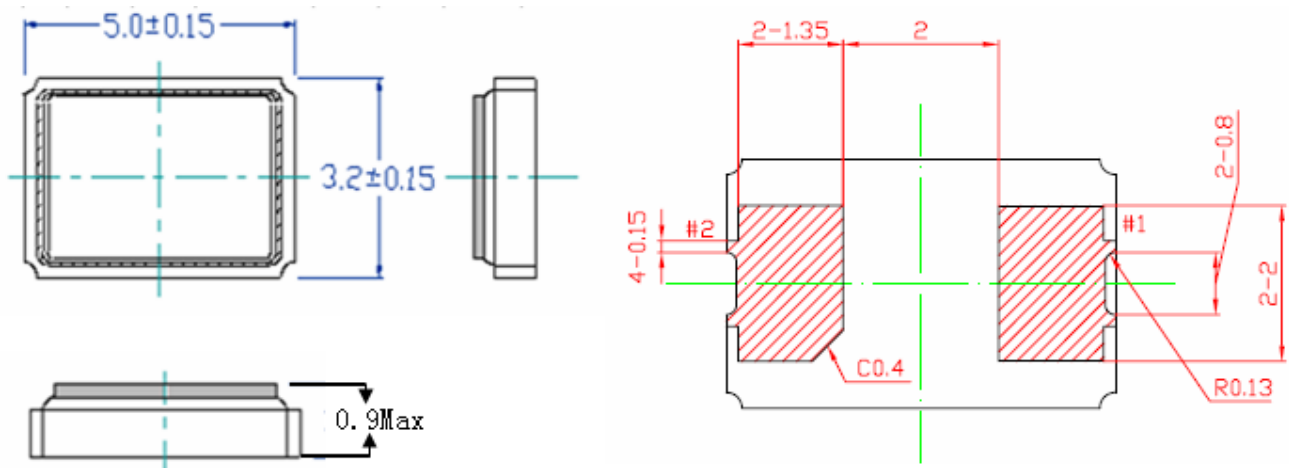
## RELIABILITY SPECIFICATIONS

NO.	TEST ITEM	TEST METHODS												
1	DROP TEST	Device are dropped from a height of 150 cm onto 2 mm thickness stainless plate executing 3 times of random drops.												
2	MECHANICAL SHOCK	Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times.												
3	VIBRATION	<table border="0"> <tr> <td>Frequency range</td> <td>10 ~ 2000 Hz</td> </tr> <tr> <td>Amplitude</td> <td>1.5 mm</td> </tr> <tr> <td>Sweep Time</td> <td>20 minute</td> </tr> <tr> <td>Test Time</td> <td>2 hours</td> </tr> </table>	Frequency range	10 ~ 2000 Hz	Amplitude	1.5 mm	Sweep Time	20 minute	Test Time	2 hours				
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4	SOLDERABILITY	<table border="0"> <tr> <td>MIL - STD - 20E Method 208C</td> <td></td> </tr> <tr> <td>Temperature</td> <td>245 ±5</td> </tr> <tr> <td>Material</td> <td>H63A (Silver 2 ~ 3 %)</td> </tr> <tr> <td>Immersion depth</td> <td>0.5 mm minimum</td> </tr> <tr> <td>Immersion time</td> <td>3 ± 0.5 seconds</td> </tr> <tr> <td>Flux</td> <td>Rosin resin methyl alcohol solvent ( 1 : 4 )</td> </tr> </table>	MIL - STD - 20E Method 208C		Temperature	245 ±5	Material	H63A (Silver 2 ~ 3 %)	Immersion depth	0.5 mm minimum	Immersion time	3 ± 0.5 seconds	Flux	Rosin resin methyl alcohol solvent ( 1 : 4 )
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5	RESISTANCE TO SOLDERING HEAT	MIL - SLD -202, Method 210, Condition I or J 10 sec immersion into 260 ± 5 solder pot, above 180 is 90 ~ 120 sec.												
6	LOW TEMP. STORAGE	Leave at - 55 ± 2 for 1000 ± 12 hours												
7	HIGH TEMP. STORAGE	Leave at 125 ± 2 for 1000 ± 12 hours												
8	THERMAL SHOCK	Total 100 cycles of the following temperature cycle												



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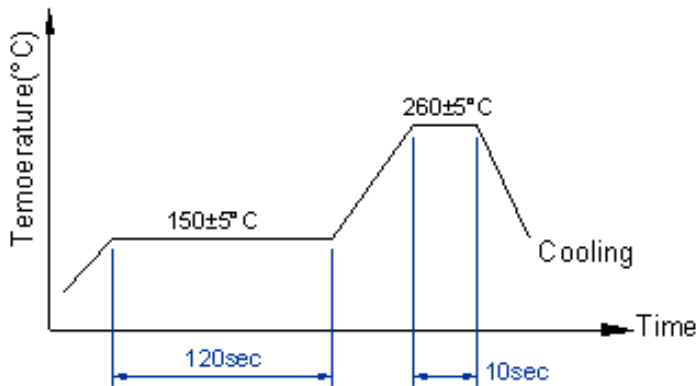
## DIMENSIONS



1	Quartz Blank
2	Electrode
3	Lid
4	Base
5	Conductive adhesive

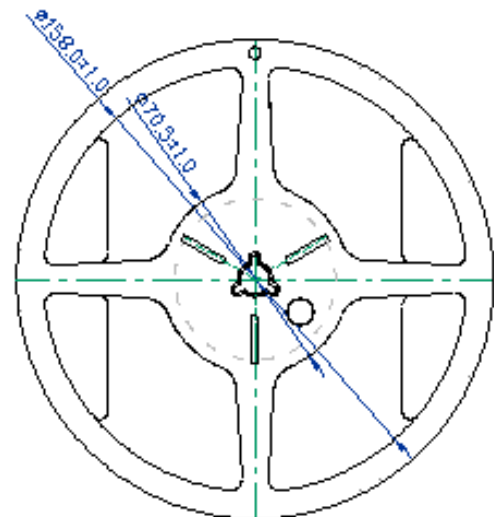
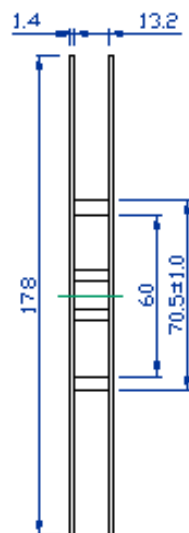
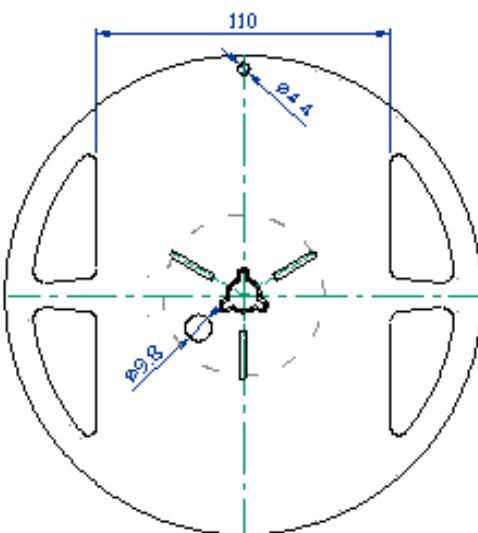
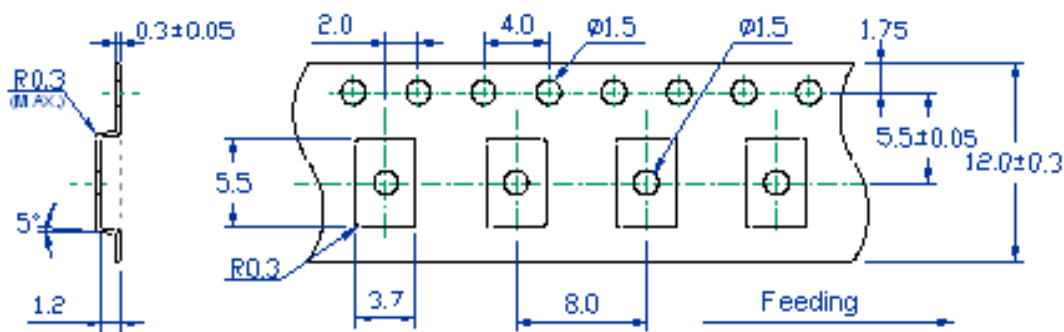
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## SUGGESTED IR REFLOW PROFILE



Total Time : 200 Sec.Max  
Solder melting point : 185

## PACKING

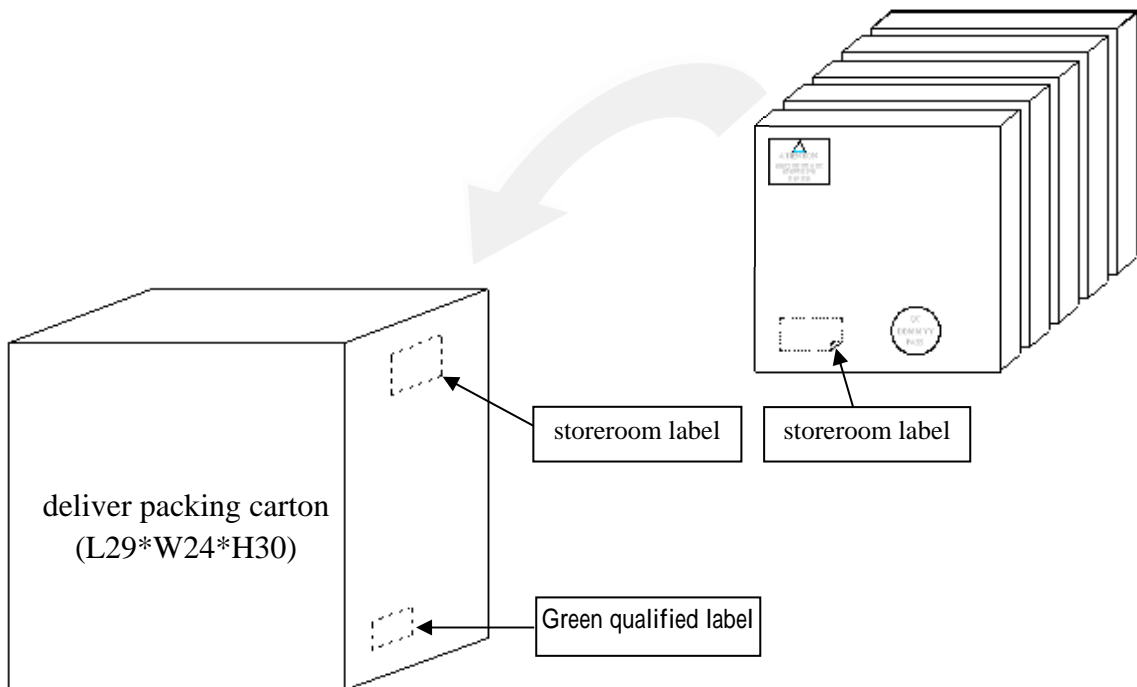
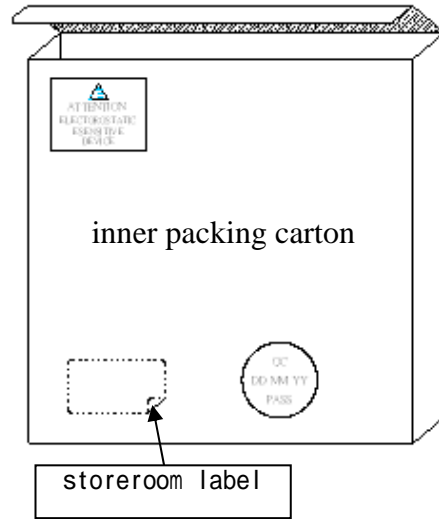
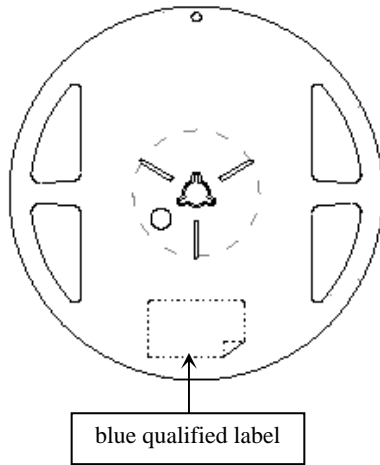
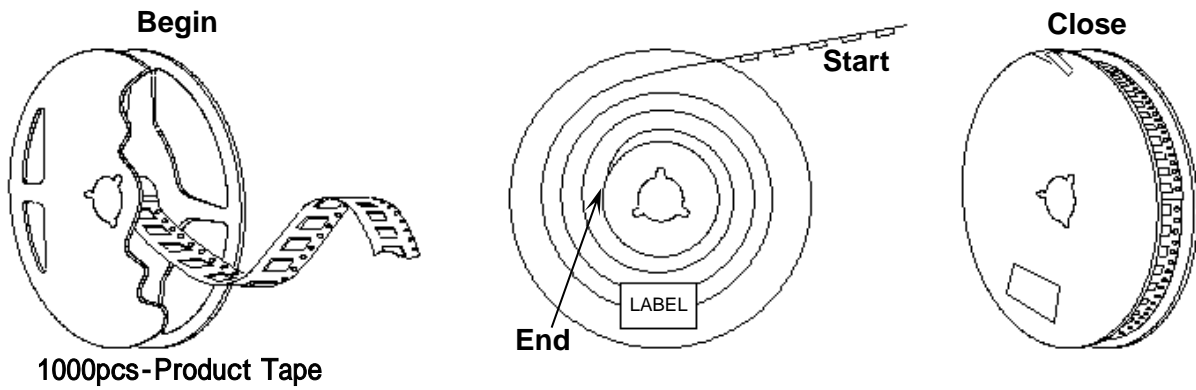


1. 230mm minimum leader which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

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